

## Description

The μPD431004 is a 262,144-word by 4-bit static RAM fabricated with advanced silicon-gate technology. CMOS peripheral circuits and N-channel memory cells with polysilicon resistors make the μPD431004 a high-speed device that requires very low power and no clock or refreshing.

The μPD431004 is available in standard 28-pin plastic SOJ packaging.

## Features

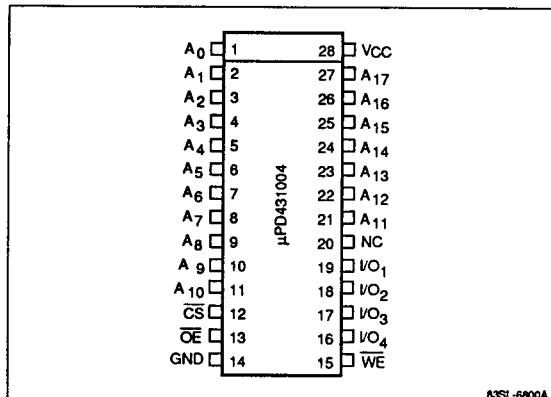
- 262,144-word x 4-bit organization
- Single +5-volt power supply
- Fully static operation—no clock or refreshing
- TTL-compatible inputs and outputs
- Common I/O capability
- Low power dissipation
  - 150 mA max (active)
  - 2 mA max (standby)
- Standard 28-pin plastic SOJ packaging

## Ordering Information

Part Number	Access Time (max)	Package
μPD431004LE-20	20 ns	28-pin plastic SOJ
LE-25	25 ns	
LE-35	35 ns	

## Pin Configuration

### 28-Pin Plastic SOJ



83SL-6800A

## Pin Identification

Symbol	Function
A <sub>0</sub> - A <sub>17</sub>	Address inputs
I/O <sub>1</sub> - I/O <sub>4</sub>	Data inputs and outputs
CS	Chip select
WE	Write enable
GND	Ground
VCC	+5-volt power supply
NC	No connection

21b

**Absolute Maximum Ratings**

Supply voltage, V <sub>CC</sub>	-0.5 to +7.0 V
Input and output voltages, V <sub>IN</sub> (Note 1)	-0.5 to V <sub>CC</sub> + 0.3
Operating temperature, T <sub>OPR</sub>	0 to +70°C
Storage temperature, T <sub>STG</sub>	-55 to +125°C
Power dissipation, P <sub>D</sub>	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

**Notes:**

- (1) V<sub>IN</sub> = -3.0 V minimum for 10 ns pulse.

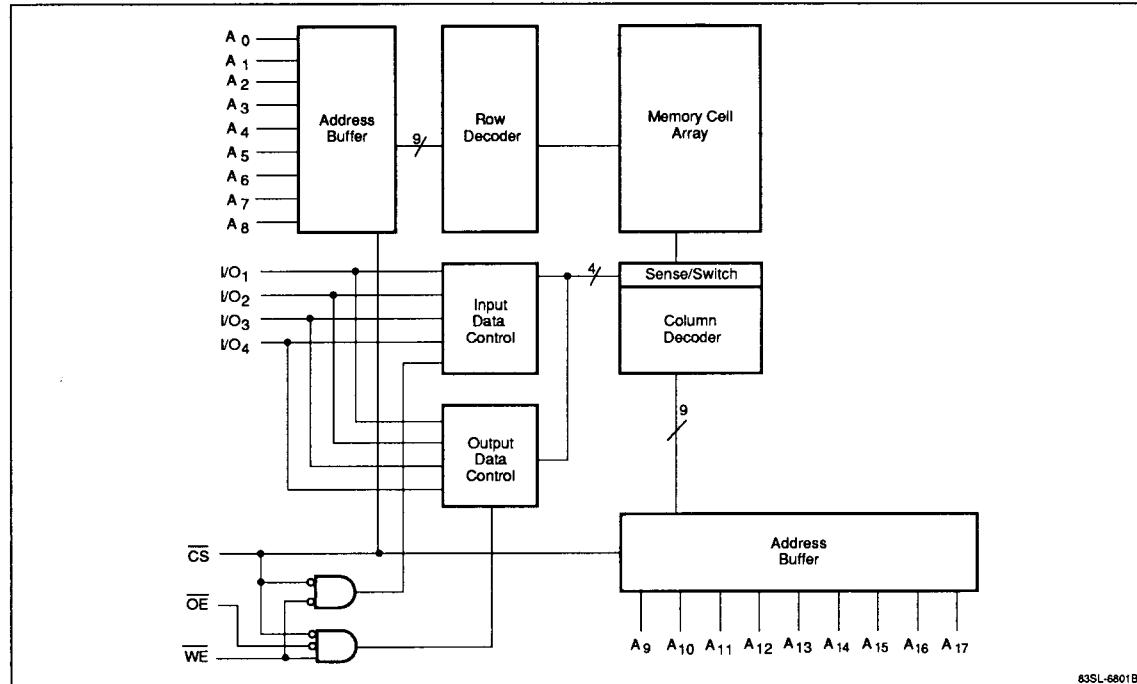
**Capacitance**

T<sub>A</sub> = 25°C; V<sub>IN</sub> and V<sub>DOUT</sub> = 0 V; f = 1 MHz (Note 1)

Parameter	Symbol	Min	Max	Unit
Input capacitance	C <sub>IN</sub>	6	pF	
Output capacitance	C <sub>DOUT</sub>	10	pF	

**Notes:**

- (1) This parameter is sampled and not 100% tested.

**Block Diagram**

**DC Characteristics** $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V} \pm 10\%$ 

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Input leakage current	$I_{IL}$	-2		2	μA	$V_{IN} = 0 \text{ V to } V_{CC}$
Output leakage current	$I_{OL}$	-2		2	μA	$V_{OUT} = 0 \text{ V to } V_{CC}; \bar{CS} = V_{IH}$ or $\bar{WE} = V_{IL}$ or $\bar{OE} = V_{IH}$
Standby supply current	$I_{SB}$			30	mA	$\bar{CS} = V_{IH}$
	$I_{SB1}$			2	mA	$\bar{CS} \geq V_{CC} - 0.2 \text{ V}; V_{IN} \leq 0.2 \text{ V} \text{ or } \geq V_{CC} - 0.2 \text{ V}$
Output voltage, low	$V_{OL}$			0.4	V	$I_{OL} = 8.0 \text{ mA}$
Output voltage, high	$V_{OH}$		2.4		V	$I_{OH} = -4.0 \text{ mA}$

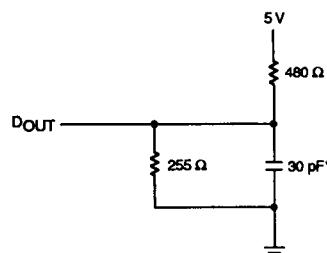
**AC Characteristics** $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V} \pm 10\%$ 

Parameter	Symbol	μPD431004-20		μPD431004-25		μPD431004-35		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
<b>Read Operation</b>									
Operating supply current	$I_{CC}$		150		140		120	mA	$\bar{CS} = V_{IL}; t_{RC} = t_{RC} (\text{min}); I_{DOUT} = 0 \text{ mA}$
Read cycle time	$t_{RC}$	20		25		35		ns	(Note 2)
Address access time	$t_{AA}$		20		25		35	ns	
Chip select access time	$t_{ACS}$		20		25		35	ns	
Output hold from address change	$t_{OH}$	5		5		5		ns	
Output enable access time	$t_{OE}$		10		10		15	ns	
Output enable to output in low-Z	$t_{OLZ}$	0		0		0		ns	(Note 3)
Output disable to output in high-Z	$t_{OHZ}$	0	8	0	10	0	15	ns	(Note 4)
Chip selection to output in low-Z	$t_{CLZ}$	5		5		5		ns	(Note 3)
Chip selection to output in high-Z	$t_{CHZ}$	0	8	0	10	0	15	ns	(Note 4)
<b>Write Operation</b>									
Write cycle time	$t_{WC}$	20		25		35		ns	(Note 2)
Chip select to end of write	$t_{CW}$	15		20		30		ns	
Address valid to end of write	$t_{AW}$	15		20		30		ns	
Address setup time	$t_{AS}$	0		0		0		ns	
Write pulse width	$t_{WP}$	15		20		30		ns	
Write recovery time	$t_{WR}$	3		3		3		ns	
Data valid to end of write	$t_{DW}$	12		12		20		ns	
Data hold time	$t_{DH}$	0		0		0		ns	
Write enable to output in high-Z	$t_{WHZ}$	0	8	0	8	0	10	ns	(Note 4)
Output active from end of write	$t_{OW}$	0		0		0		ns	(Note 3)

**Notes:**

- (1) Input pulse levels = GND to 3.0 V; input pulse rise and fall times = 3 ns; timing reference levels = 1.5 V; see figures 1 and 2 for output load.
- (2) All read cycle timings are referenced from the last valid address to the first transitioning address.
- (3) Transition is measured at  $\pm 200 \text{ mV}$  from steady-state voltage with the load shown in figure 2.
- (4) Transition is measured at  $V_{OL} + 200 \text{ mV}$  and  $V_{OH} - 200 \text{ mV}$  with the load shown in figure 2.

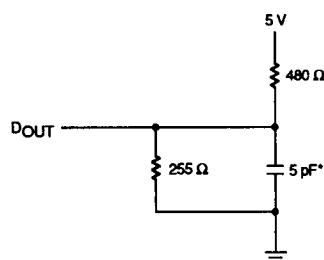
**Figure 1. Output Load**



\*Including Scope and Jig

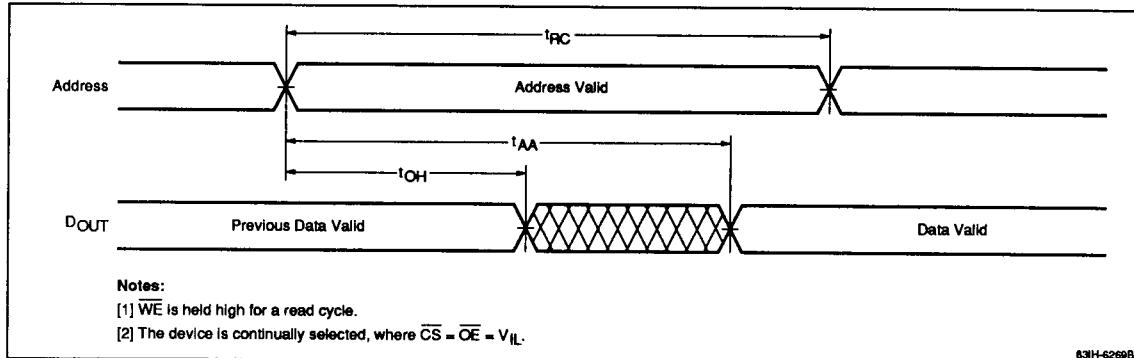
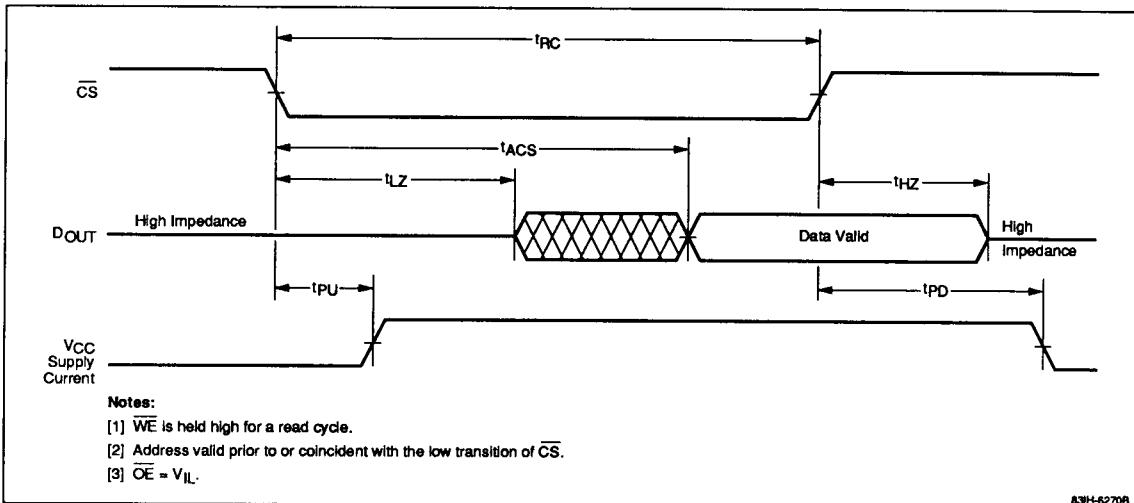
83H-4832A

**Figure 2. Output Load for  $t_{CHZ}$ ,  $t_{CLZ}$ ,  $t_{OHZ}$ ,  $t_{OLZ}$ ,  $t_{WHz}$ , and  $t_{OW}$**



\*Including Scope and Jig

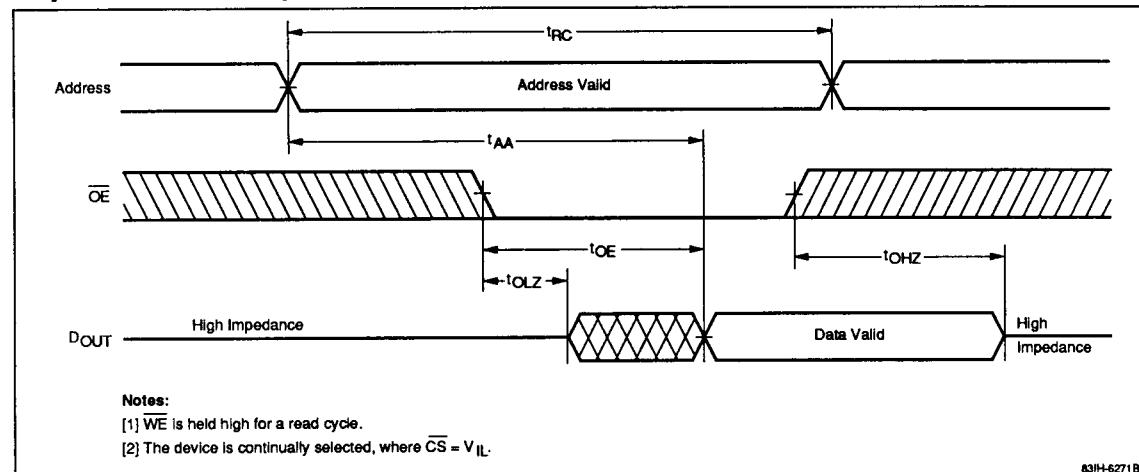
83H-4831A

**Timing Waveforms****Address Access Cycle****Chip Select Access Cycle**

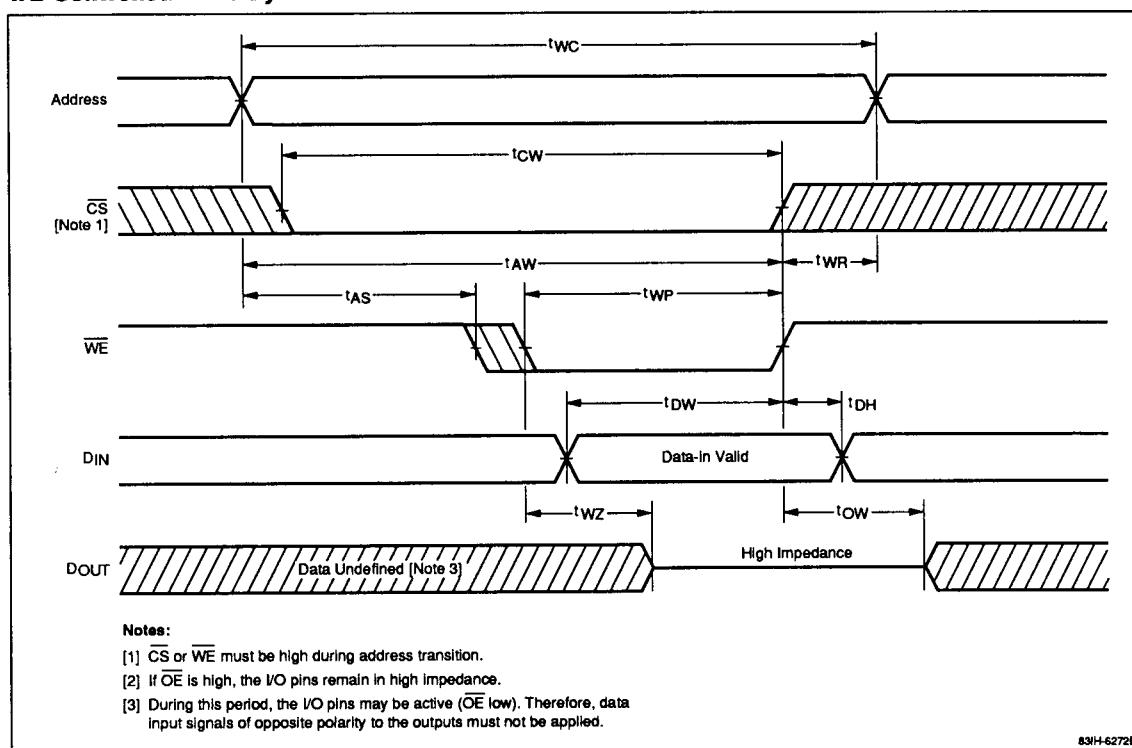
21b

### Timing Waveforms (cont)

#### Output Enable Access Cycle



#### WE-Controlled Write Cycle



## Timing Waveforms (cont)

**CS-Controlled Write Cycle**